## 電子工程專輯

## **EETT Editorial Calendar 2024**

Issue	Cover Story	Trend & Analysis				Design & Technology	
		Technology Trends	Opinions	Interview	Innovative Products	Design Corner	Test and Measurement
<b>January</b> Ad Booking Deadline: 23-Nov-2023 Ad Materials Deadline: 28-Nov-2023	New year outlook					PCB Design High Frequency Design Embedded Design	Power Integrity Measurement
<b>February (Digital)</b> Ad Booking Deadline: 22-Dec-2023 Ad Materials Deadline: 28-Dec-2023	The road to commercialization of MicroLED		•			Mixed Signal Circuit Design Data Security and Encryption MCU	Microwave RF Test
March Ad Booking Deadline: 19-Jan-2024 Ad Materials Deadline: 22-Jan-2024	EDA technology and industry trends					Smart Grid Wireless Communication Analog Circuit Design	Oscilloscope
April Ad Booking Deadline: 23-Feb-2024 Ad Materials Deadline: 28-Feb-2024	GPU/image processor					LED Lighting Photoelectric and Display MEMS Sensor	EMI Test
May Ad Booking Deadline: 22-Mar-2024 Ad Materials Deadline: 28-Mar-2024	Motor drive and control					Motor Control RF/Microwave Servo Control	Network Analyzer
<b>June</b> Ad Booking Deadline: 23-Apr-2024 Ad Materials Deadline: 29-Apr-2024	LLM and semiconductor industry					Wearable Gadget Design nergy Acquisition Digital Signal Processing	Test Software /IP
July Ad Booking Deadline: 23-May-2024 Ad Materials Deadline: 28-May-2024	Automobile intelligence and connectivity					Medical Electronics ADC/DAC Edge Computing	Signal Integrity Measurement
August Ad Booking Deadline: 21-Jun-2024 Ad Materials Deadline: 28-Jun-2024	3D-IC/3D NAND					Audio Design FPGA/DSP Wafer Foundry	Impedance Measurement
September Ad Booking Deadline: 23-Jul-2024 Ad Materials Deadline: 26-Jul-2024	Foundry/ANG process					EMI/EMC Circuit Protection Ladar Technology	Embedded System Test
<b>October</b> Ad Booking Deadline: 23-Aug-2024 Ad Materials Deadline: 28-Aug-2024	RISC-V architecture ecology					Human-Machine Interaction Touch Technology Speech Recognition / Processing	Mixed Signal Measurement
November Ad Booking Deadline: 22-Sep-2024 Ad Materials Deadline: 27-Sep-2024	Advanced packaging technology					Power Device Low Power Design Digital Power	Vector Signal Analysis
December  Ad Booking Deadline: 23-Oct-2024  Ad Materials Deadline: 28-Oct-2024	Silicon carbide/wide bandgap semiconductor					5G Communication Wireless Connection Video Surveillance	Spectrum Analyzer

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**Note:** The publisher reserves the right to reschedule any topic in the calendar.